

RD Number: RD127

RD Title: TB67S128FTG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	CVM1	1	100 μ F 50V	–	–	Electrolytic capacitor		
2	CVM2	1	0.1 μ F 50V	–	–	Ceramic capacitor		
3	CCPO	1	0.22 μ F 50V	–	–	Ceramic capacitor		
4	CCP	1	0.022 μ F 50V	–	–	Ceramic capacitor		
5	R_RSA	0	0.22 Ω 1W	–	–	Chip resistor		✓
6	R_RSB	0	0.22 Ω 1W	–	–	Chip resistor		✓
7	RS1	1	Jumper	–	–	Short		
8	RS2	1	Jumper	–	–	Short		
9	R_LTH	1	100k Ω 0.25W	–	–	Leaded resistor		
10		2	Socket pin	–	–	Socket pin		
11	R_VREF1	0	Not mount	–	–	Leaded resistor		✓
12		2	Socket pin	–	–	Socket pin		
13	R_VREF2	0	Not mount	–	–	Leaded resistor		✓
14		2	Socket pin	–	–	Socket pin		
15	R_BST1	1	100k Ω 0.25W	–	–	Chip resistor		
16	R_BST2	1	100k Ω 0.25W	–	–	Chip resistor		
17	R_FLM1	1	100k Ω 0.25W	–	–	Chip resistor		
18	R_FLM2	1	100k Ω 0.25W	–	–	Chip resistor		
19	R_CLIM11	1	100k Ω 0.25W	–	–	Chip resistor		
20	R_CLIM12	1	100k Ω 0.25W	–	–	Chip resistor		
21	R_OSC	1	5.1k Ω 0.25W	–	–	Leaded resistor		
22		2	Socket pin	–	–	Socket pin		
23	C_OSC	1	270pF 1000V	–	–	Ceramic capacitor		
24	R_MO	1	10k Ω 0.25W	–	–	Chip resistor		
25	C_VCC	1	0.1 μ F 100V	–	–	Ceramic capacitor		
26	C_VREF	1	0.1 μ F 100V	–	–	Ceramic capacitor		

27	C_VDD	1	10 μ F 16V	–	–	Electrolytic capacitor		
28	R_LO0	1	10k Ω 0.25W	–	–	Chip resistor		
29	R_LO1	1	10k Ω 0.25W	–	–	Chip resistor		
30	C_OUTA+	0	1000pF	–	–	Ceramic capacitor		✓
31	C_OUTA-	0	1000pF	–	–	Ceramic capacitor		✓
32	C_OUTB-	0	1000pF	–	–	Ceramic capacitor		✓
33	C_OUTB+	0	1000pF	–	–	Ceramic capacitor		✓
34	SW1, SW2, SW17, SW18	4	Pin header	–	–	Jumper		
35		4	Jumper socket	–	–	Short pin		
36	SW3 to SW11, SW13 to SW16, SW19	14	Toggle switch	–	–	Toggle switch		
37	SW22 to SW24	3	Rotary switch	–	–	Rotary switch		
38	JP_VDD	1	Pin header 2P	–	–	Jumper		
39		1	Jumper socket	–	–	Short pin		
40	CN1	1	Connector 4P	–	–	Connector 4P-2.5		
41	OSCM	1	Check terminal	–	–	Check pin		
42	CLIM0	1	Check terminal	–	–	Check pin		
43	CLIM1	1	Check terminal	–	–	Check pin		
44	FLM	1	Check terminal	–	–	Check pin		
45	BST	1	Check terminal	–	–	Check pin		
46	IF_SEL	1	Check terminal	–	–	Check pin		
47	VCC	1	Check terminal	–	–	Check pin		
48	RSA	1	Check terminal	–	–	Check pin		
49	OUT_A+	1	Check terminal	–	–	Check pin		
50	OUT_A-	1	Check terminal	–	–	Check pin		
51	OUT_B-	1	Check terminal	–	–	Check pin		
52	OUT_B+	1	Check terminal	–	–	Check pin		
53	RSB	1	Check terminal	–	–	Check pin		
54	VM	1	Check terminal	–	–	Check pin		
55	MDT0	1	Check terminal	–	–	Check pin		
56	MDT1	1	Check terminal	–	–	Check pin		
57	TORQE0	1	Check terminal	–	–	Check pin		
58	TORQE1	1	Check terminal	–	–	Check pin		

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